

FIG - 1

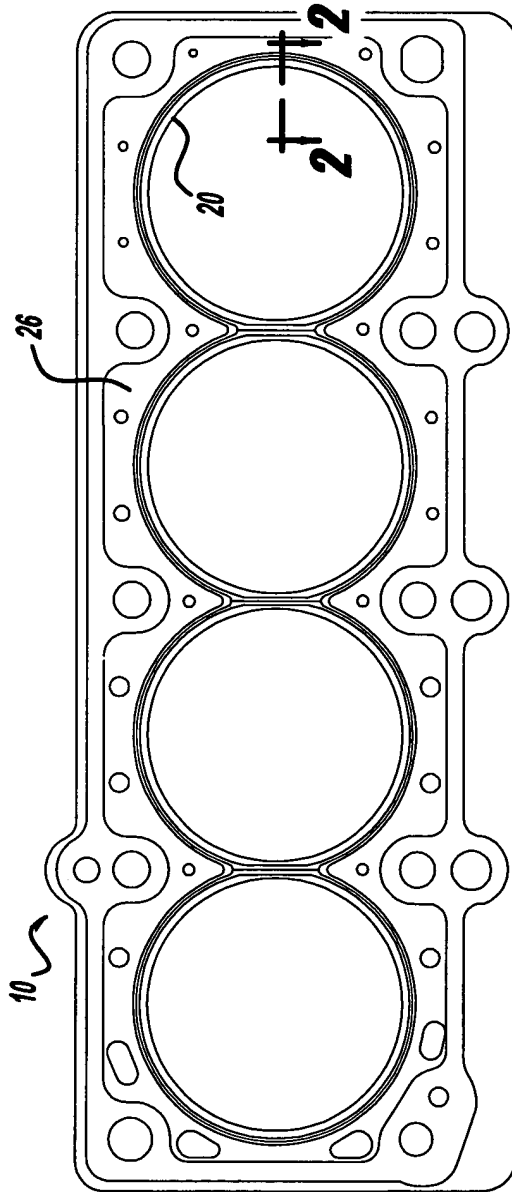
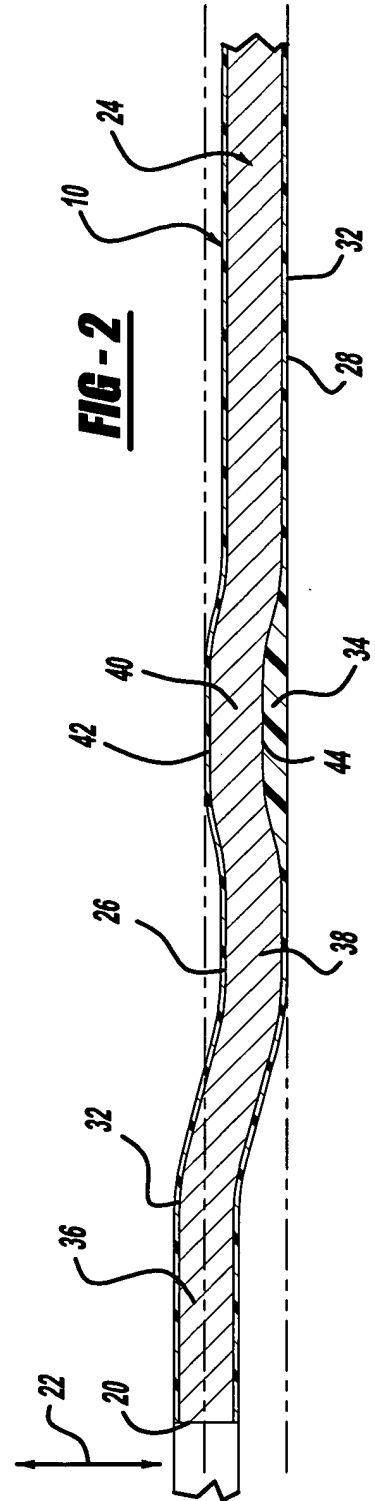


FIG - 2



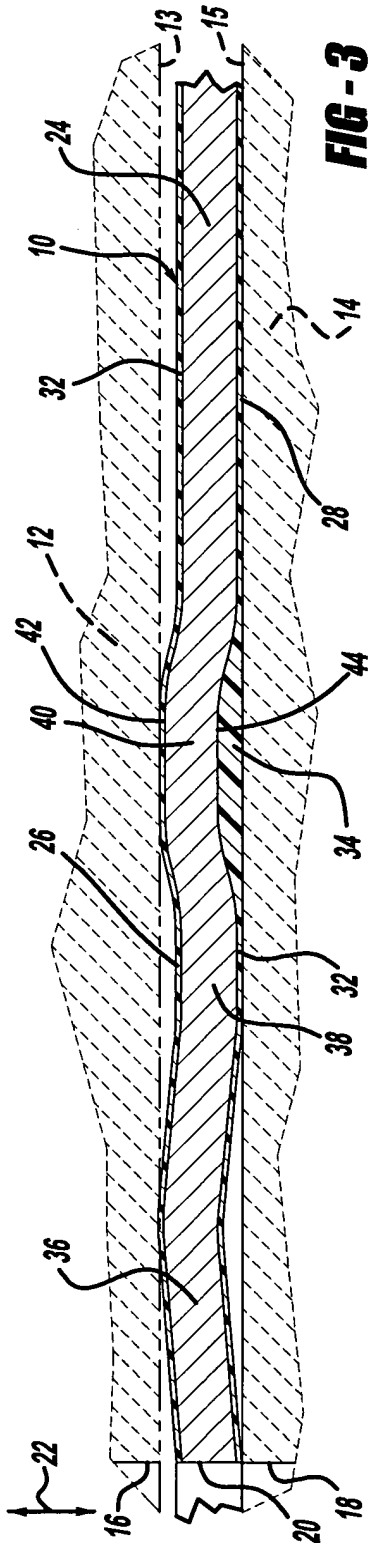


FIG - 3

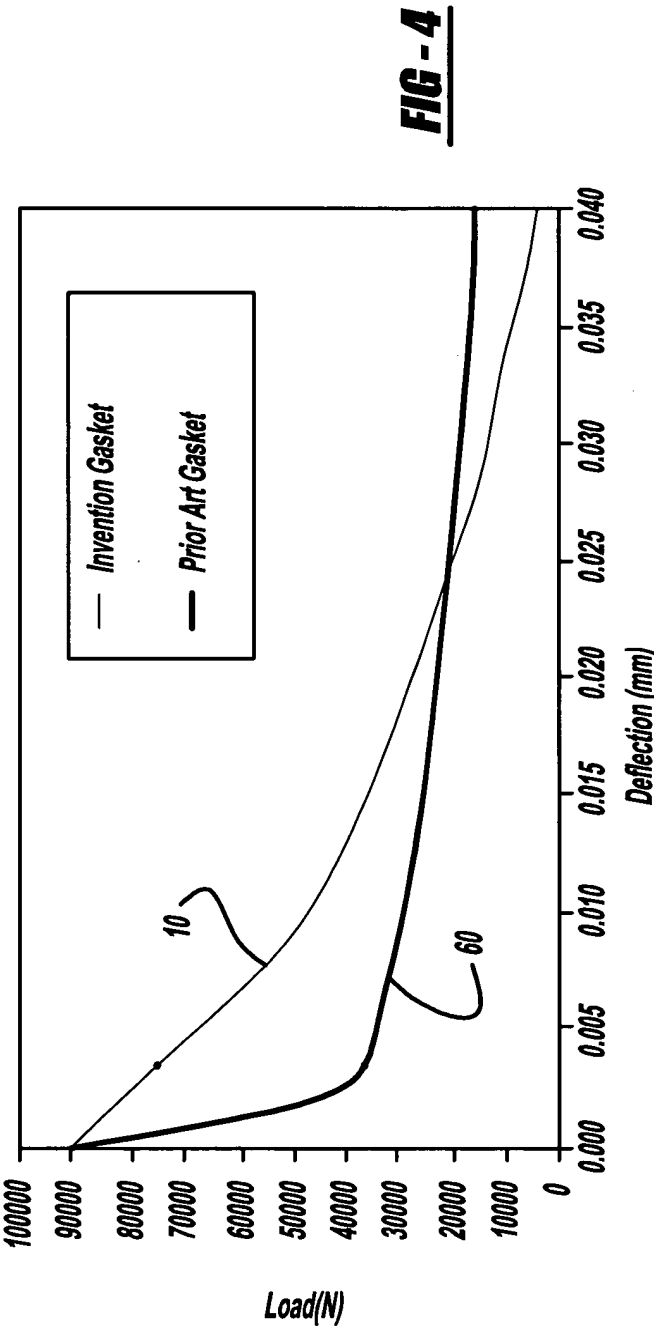
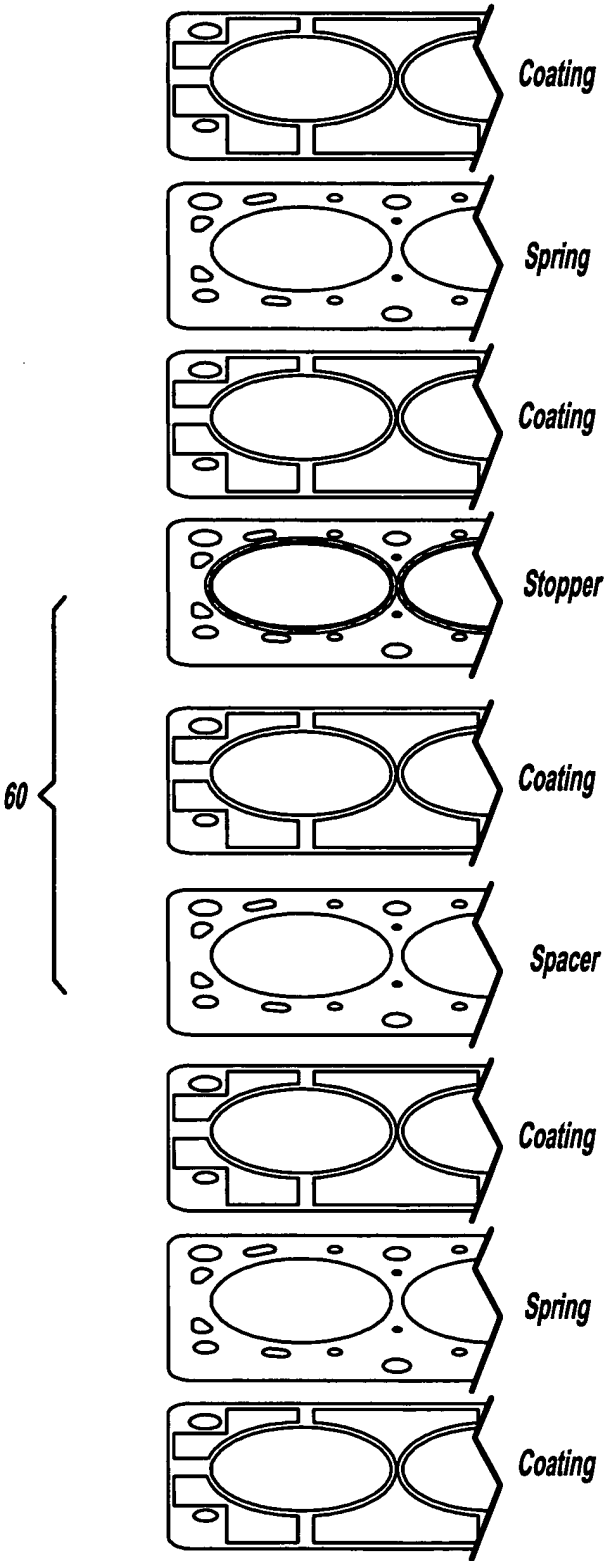


FIG - 4

FIG - 5
Prior Art



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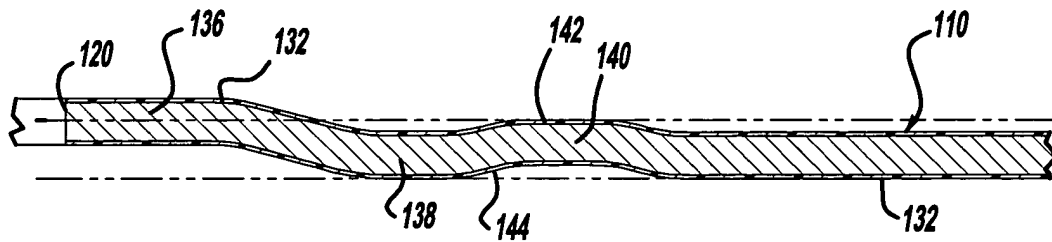
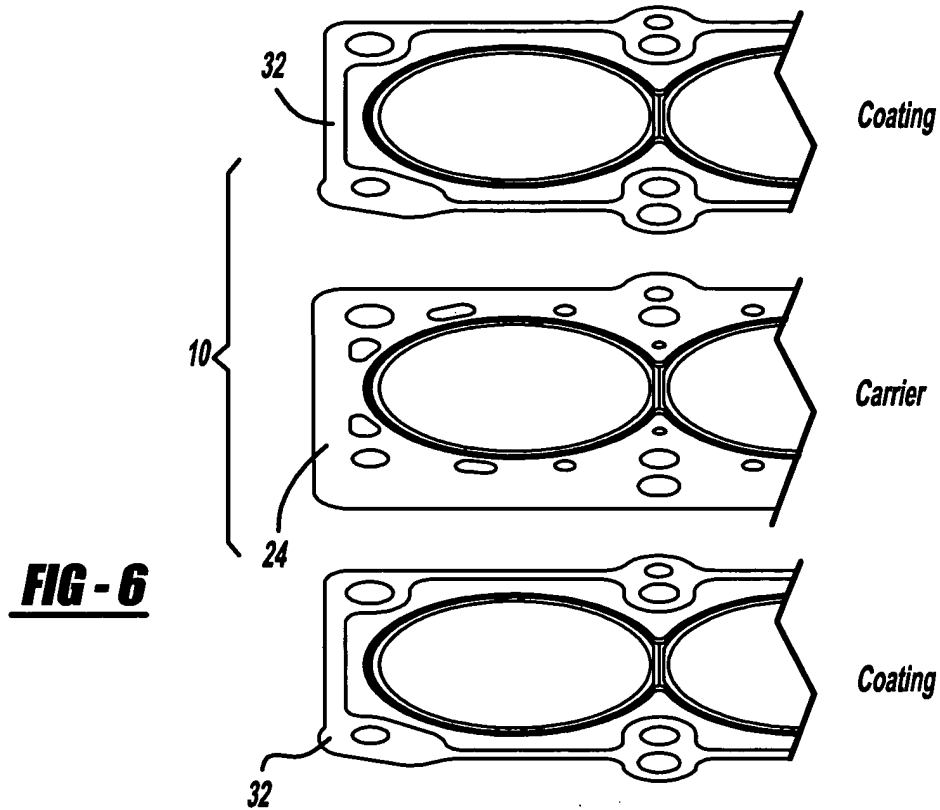


FIG - 9

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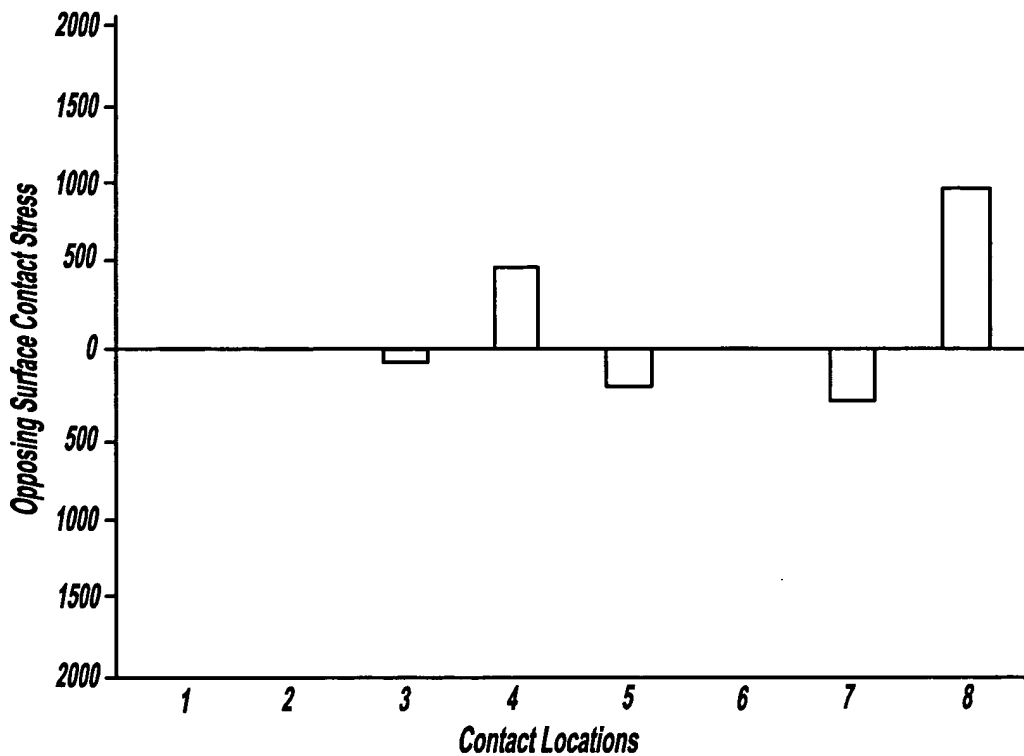


FIG - 7a
PRIOR ART

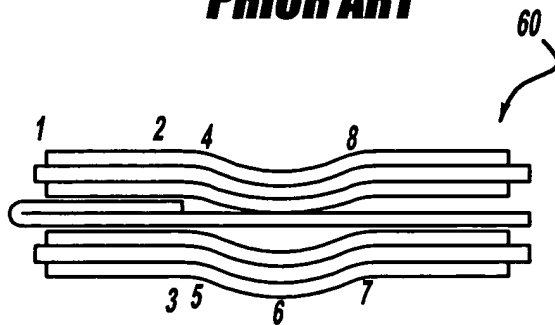


FIG - 7b
PRIOR ART

FIG - 8b

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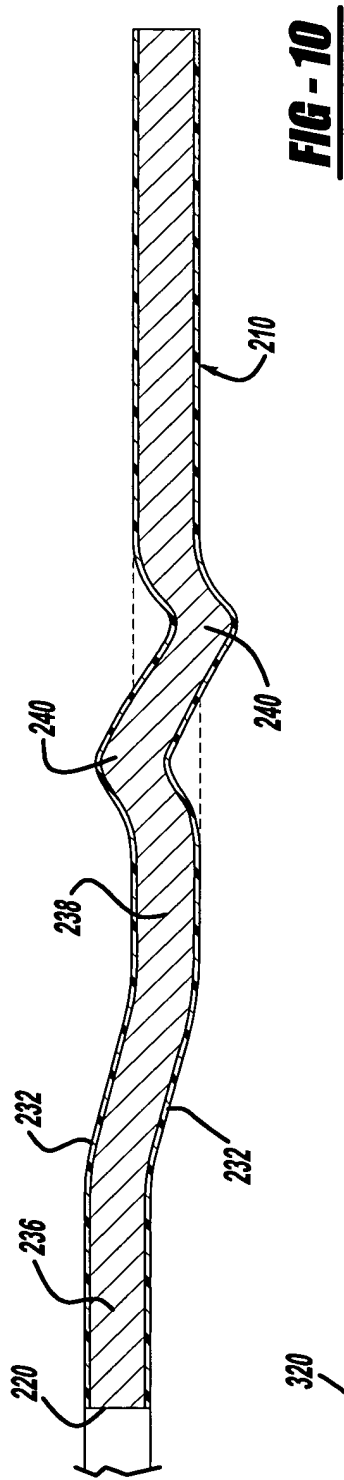


FIG - 10

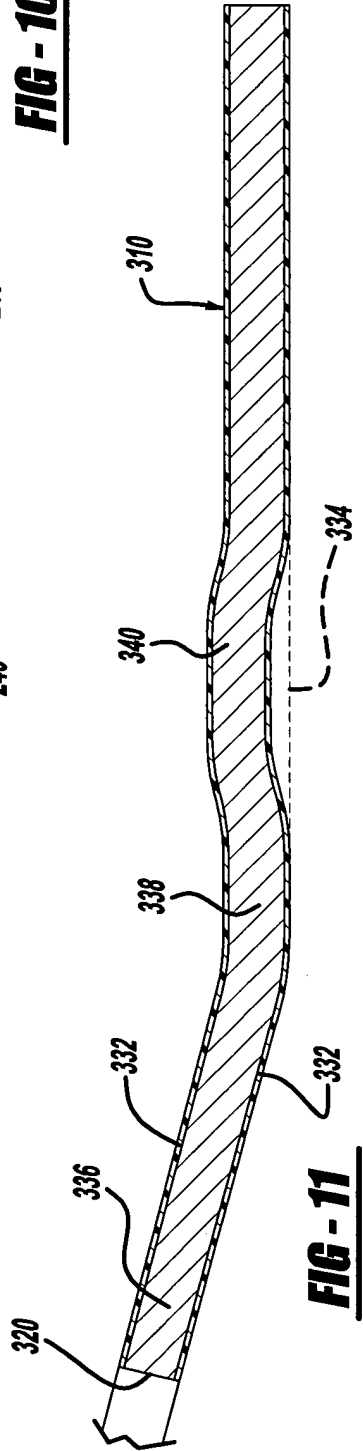


FIG - 11

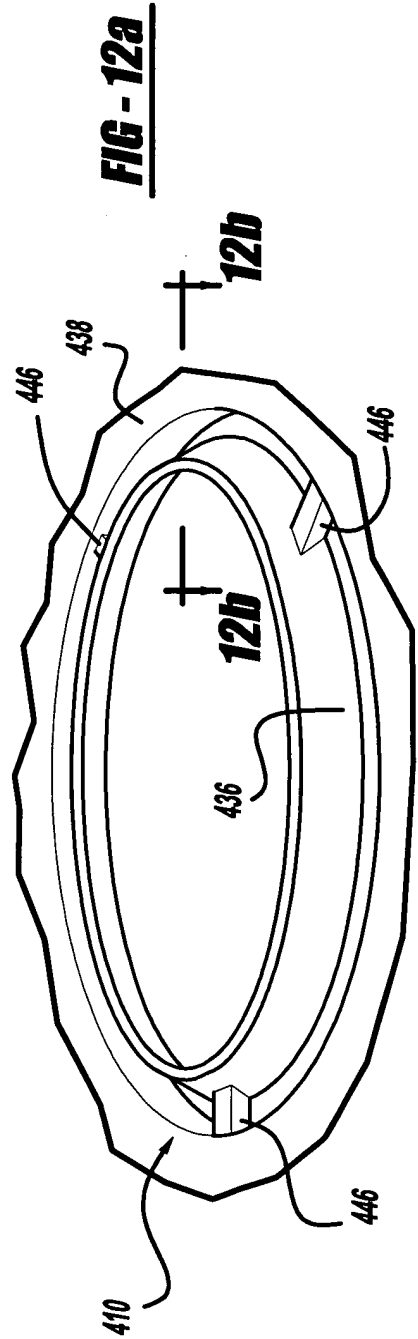
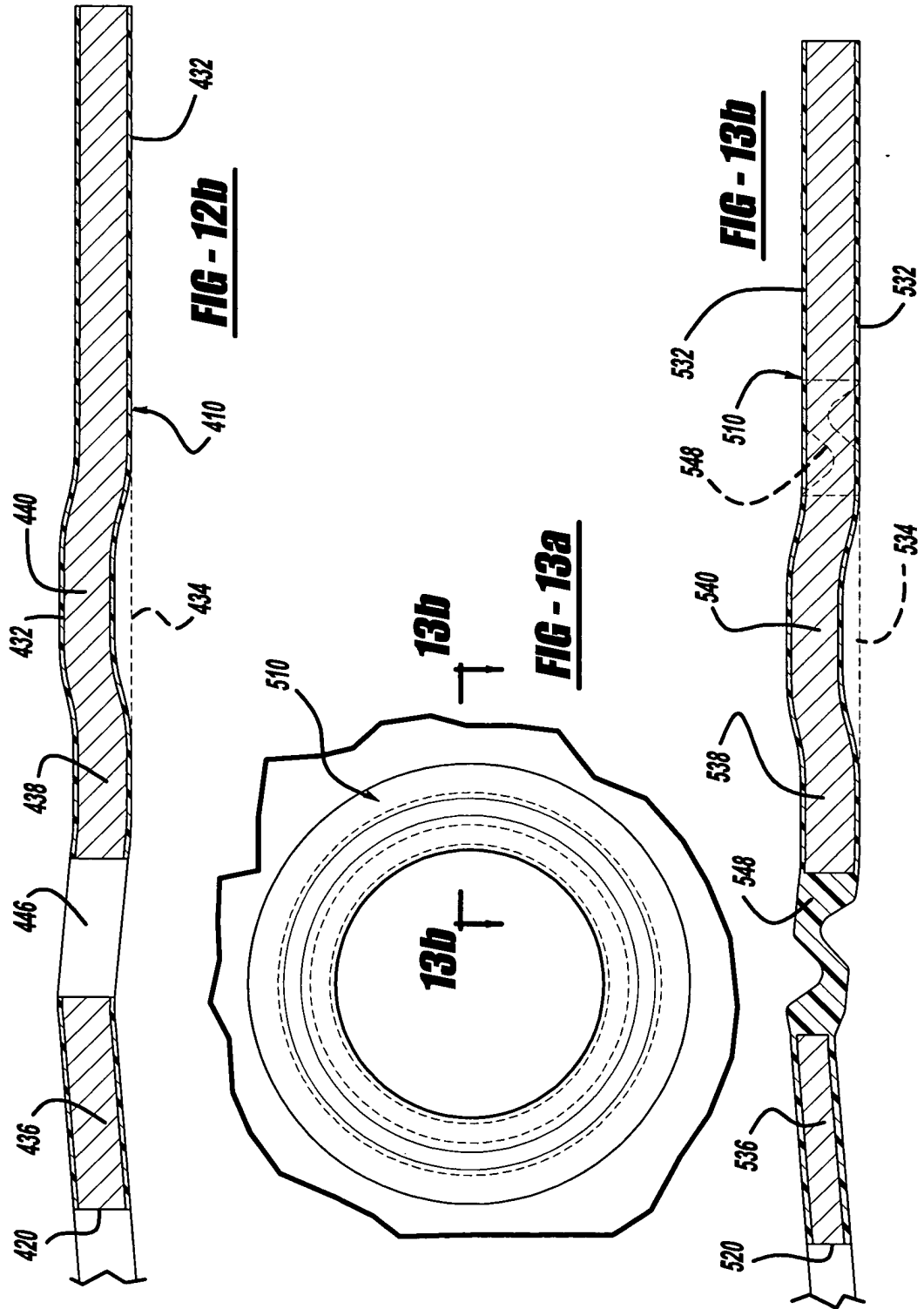
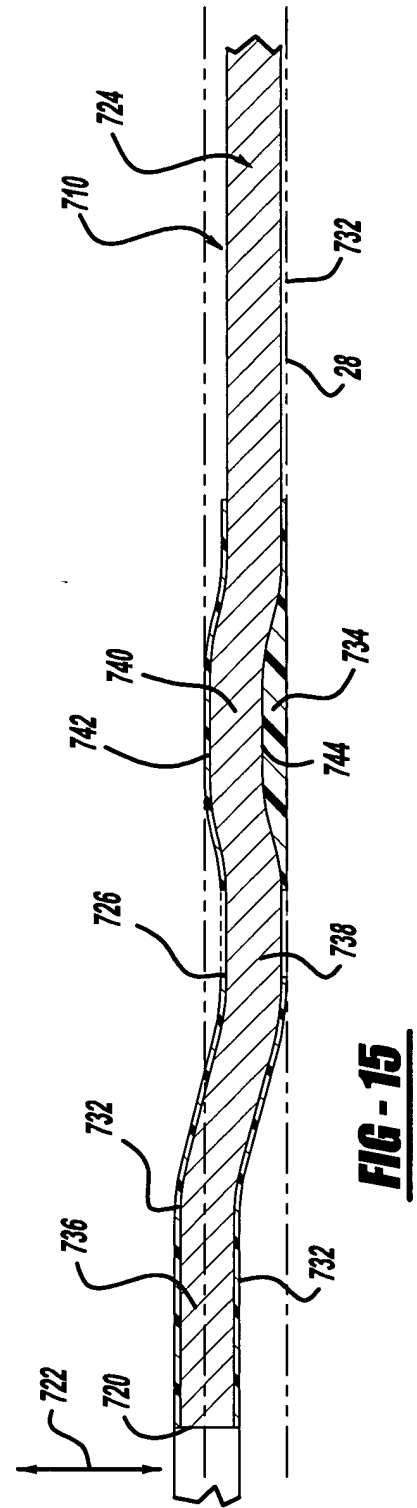
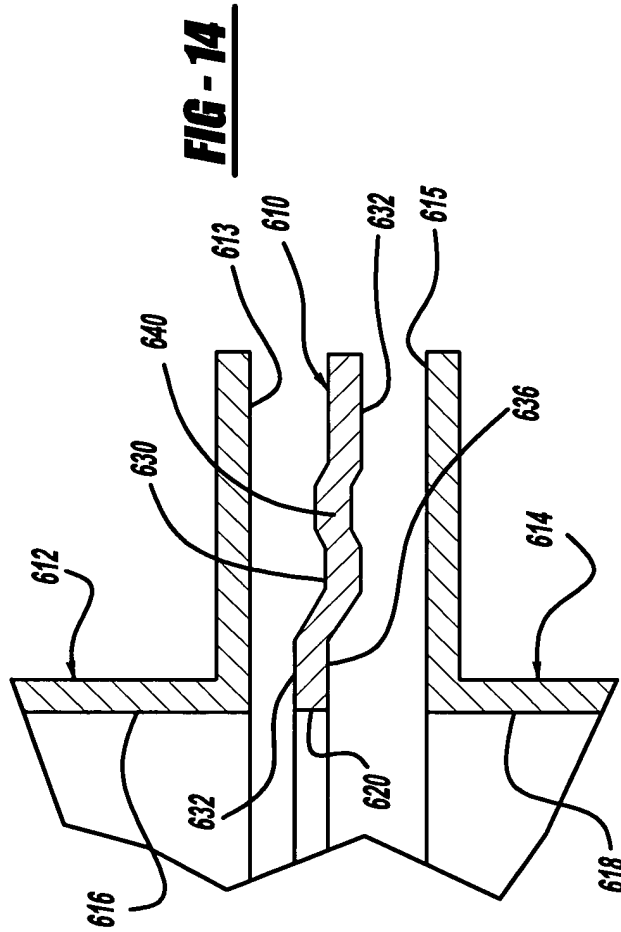


FIG - 12a



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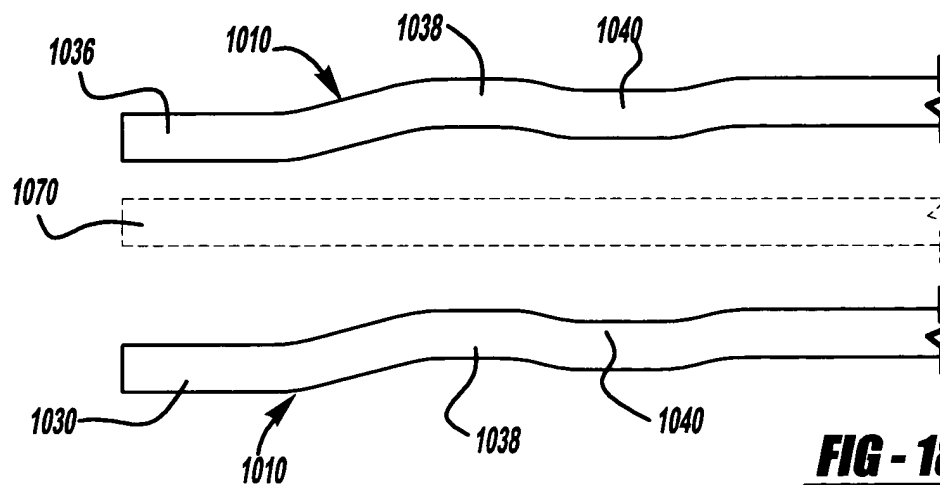
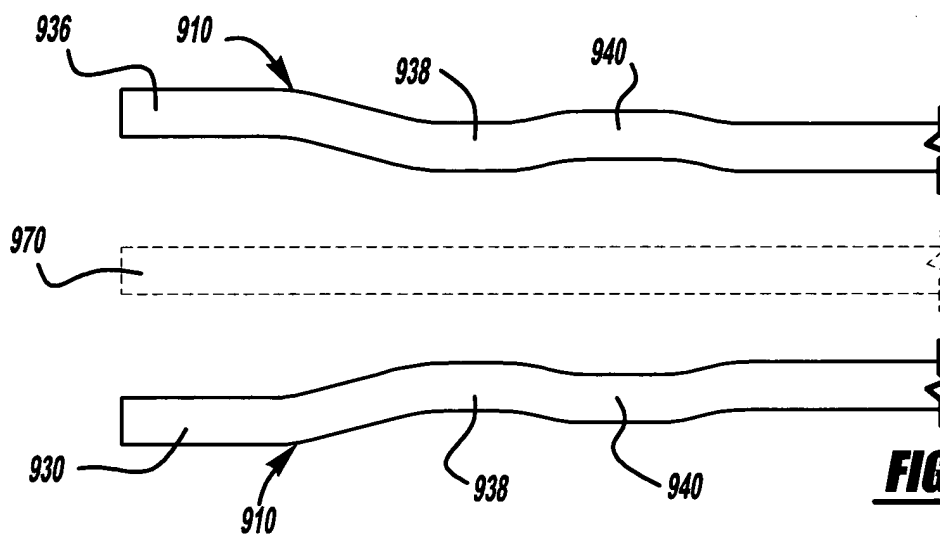
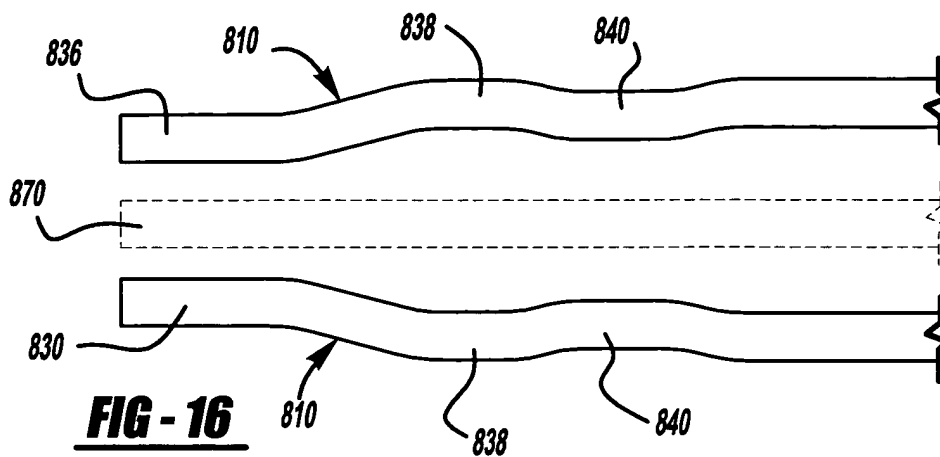


FIG. 12 is a cross-sectional view of a device 1200. The device includes a substrate 1236, a layer 1210, a layer 1238, and a layer 1240. A dashed line 1270 is shown below the substrate 1236.

FIG - 20